

## ABSTRACT OF THE DISCLOSURE

The cleaning composition of the present invention is characterized by containing N-hydroxyformamide. The cleaning composition is capable of easily removing patterned photoresist masks or resist residues remaining on  
5 substrates after the etching process or removing resist residues remaining after the etching process and the subsequent ashing process within a short period of time without causing the corrosion of wiring materials and insulating films, thereby ensuring the fine processing to provide high-precision wiring circuits.